

IN THE CLAIMS:

All of the claims that remain pending and under consideration in the above-referenced application are presented, pursuant to 37 C.F.R. §§ 1.121(c)(1)(i) and 1.121(c)(3), in clean form below. Claims 1, 3, and 5 through 15 have been amended herein. Please enter these claims as amended. Also attached is a marked-up version of the claims, as amended herein, pursuant to 37 C.F.R. § 1.121(c)(1)(ii).

Please amend the claims as follows:

- Sub C1*
- B2*
1. (Twice Amended) An overlay target comprising:
at least one trench having a bottom surface, said one trench including a series of substantially vertically extending laterally continuous raised lines originating at said bottom surface of said trench.
 2. The overlay target of claim 1, wherein said at least one trench comprises a continuous trench defining a geometric shape.
 3. (Twice Amended) The overlay target of claim 1, wherein said at least one trench comprises a plurality of trenches defining said overlay target, each of said plurality of trenches includes said series of substantially vertically extending laterally continuous raised lines originating at said bottom surface of said trench.
 4. The overlay target of claim 3, wherein said plurality of trenches includes at least one continuous trench defining a geometric shape.
 5. (Twice Amended) An overlay target comprising:
at least one pad area having a bottom surface, said one pad area including a series of substantially vertically extending laterally continuous raised lines originating at said bottom surface of said pad area.

6. (Twice Amended) The overlay target of claim 5, wherein said at least one pad area includes a plurality of pad areas defining said overlay target, each of said plurality of pad areas includes said series of substantially vertically extending laterally continuous raised lines originating at said bottom surface of said pad area.

7. (Twice Amended) The overlay target of claim 6, further comprising at least one trench including said series of substantially vertically extending laterally continuous raised lines originating at a bottom surface of said overlay target.

8. (Twice Amended) A semiconductor wafer comprising:
a semiconductor substrate; and
an overlay target having a bottom surface comprising at least one series of substantially vertically extending laterally continuous raised lines originating at said bottom surface of said overlay target.

9. (Twice Amended) The semiconductor wafer of claim 8, wherein said at least one series of substantially vertically extending laterally continuous raised lines is etched into said semiconductor substrate.

10. (Twice Amended) The semiconductor wafer of claim 8, wherein said at least one series of substantially vertically extending laterally continuous raised lines is etched into a material layer overlying said semiconductor substrate.

11. (Twice Amended) The semiconductor wafer of claim 8, wherein said at least one series of substantially vertically extending laterally continuous raised lines is disposed in at least one trench.

12. (Twice Amended) The semiconductor wafer of claim 11, wherein a plurality of trenches and a corresponding plurality of series of substantially vertically extending laterally continuous raised lines define said overlay target, each of said plurality of trenches includes one of said plurality of series of substantially vertically extending raised lines.

13. (Twice Amended) The semiconductor wafer of claim 8, wherein said at least one series of substantially vertically extending laterally continuous raised lines is disposed in at least one pad area.

14. (Twice Amended) The semiconductor wafer of claim 13, wherein a plurality of pad areas and a corresponding plurality of series of substantially vertically extending laterally continuous raised lines define said overlay target, each of said plurality of pad areas includes one of said plurality of series of substantially vertically extending laterally continuous raised lines.

15. (Twice Amended) The semiconductor wafer of claim 8, wherein said at least one series of substantially vertically extending laterally continuous raised lines comprises a first series of raised lines disposed in a pad area and a second series of raised lines disposed in a trench.

IN THE DRAWINGS:

Pursuant to 37 C.F.R. § 1.121(d), Applicants are submitting proposed changes to Figs. 1, 3, 4, 8, 13, and 14 and herein request Examiner's approval for such changes. These figures are enclosed herein on a separate paper showing the proposed changes in red. The minor changes being proposed to these figures do not add new matter to the above-referenced application and are requested to (i) correct in FIG. 1 the references to elements 5 and 10 in agreement with their discussion in the description and to remove element 12 not mentioned therein; (ii) renumber elements 24 and 26 in FIG. 2 in agreement with their references in the description; (iii) add the missing label for element 11 in FIG. 4; (iv) add the missing label for element 39 in FIG. 8; and (v) appropriately label FIGS. 13 and 14 by switching their figure numbers in agreement with their discussion in the specifications. Upon approval, Applicants will file new drawings in compliance with 37 C.F.R. § 1.84.